Celanese
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HOSTAFORM® C 9021 SW XAP®2 LS

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Chemical abbreviation according to ISO 1043-1: POM-KD10
Molding compound ISO 29988-POM-K,KD10,GLNRS2,3-2
POM copolymer Injection molding type, special modified with anti-friction additives for prevention of squeaking noise; good chemical resistance to solvents, fuel and strong alkalis as well as good hydrolysis resistance; high resistance to thermal and oxidative degradation. Ranges of applications: For sliding combinations with low wear and low coefficient of friction, prevents squeaking noise. Burning rate ISO 3795 and FMVSS 302 < 100 mm/min for a thickness more than 1,5 mm. Reduced emission grade. Emissions according to VDA 275 < 5 mg/kg Preliminary Datasheet

Product information

Resin Identification	POM-KD10	ISO 1043
Part Marking Code	>POM-KD10<	ISO 11469

Rheological properties

Melt volume-flow rate	7	cm^3/10min	ISO 1133
Temperature	190	°C	
Load	2.16	kg	

Typical mechanical properties

Tensile modulus	2700	MPa	ISO 527-1/-2
Tensile stress at yield, 50mm/min	52	MPa	ISO 527-1/-2
Tensile strain at yield, 50mm/min	7	%	ISO 527-1/-2
Nominal strain at break	16	%	ISO 527-1/-2
Flexural modulus	2600	MPa	ISO 178
Flexural strength	63	MPa	ISO 178
Charpy impact strength, 23°C	90	kJ/m^2	ISO 179/1eU
Charpy impact strength, -30°C	85	kJ/m^2	ISO 179/1eU
Charpy notched impact strength, 23°C	4	kJ/m^2	ISO 179/1eA
Charpy notched impact strength, -30°C	4	kJ/m^2	ISO 179/1eA
Ball indentation hardness, H 358/30	135	MPa	ISO 2039-1
Poisson's ratio	0.38[C]		

[C]: Calculated

Thermal properties

Melting temperature, 10°C/min	166	°C	ISO 11357-1/-3
Temperature of deflection under load, 1.8 MPa	80	°C	ISO 75-1/-2
Coefficient of linear thermal expansion (CLTE), parallel	120	E-6/K	ISO 11359-1/-2

Flammability

FMVSS Class	B		ISO 3795 (FMVSS 302)
Burning rate, Thickness 2 mm	58.8	mm/min	ISO 3795 (FMVSS 302)

Physical/Other properties

Density	1420	kg/m^3	ISO 1183

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Injection

Drying Recommended	no	
Drying Temperature	100	°C
Drying Time, Dehumidified Dryer	3 - 4	h
Processing Moisture Content	≤0.2	%
Melt Temperature Optimum	200	°C
Min. melt temperature	190	°C
Max. melt temperature	210	°C
Screw tangential speed	≤0.3	m/s
Mold Temperature Optimum	100	°C
Min. mould temperature	80	°C
Max. mould temperature	120	°C
Hold pressure range	60 - 120	MPa
Back pressure	2	MPa

Characteristics

Processing	Injection Moulding, Other Extrusion
Delivery form	Pellets
Additives	Release agent
Special characteristics	U.V. stabilised or stable to weather, Low wear / Low friction, Low emissions

Additional information

Processing Notes

Storage

The product can then be stored in standard conditions until processed.

Automotive

OEM	STANDARD	ADDITIONAL INFORMATION
Mercedes-Benz	DBL5404	BQF

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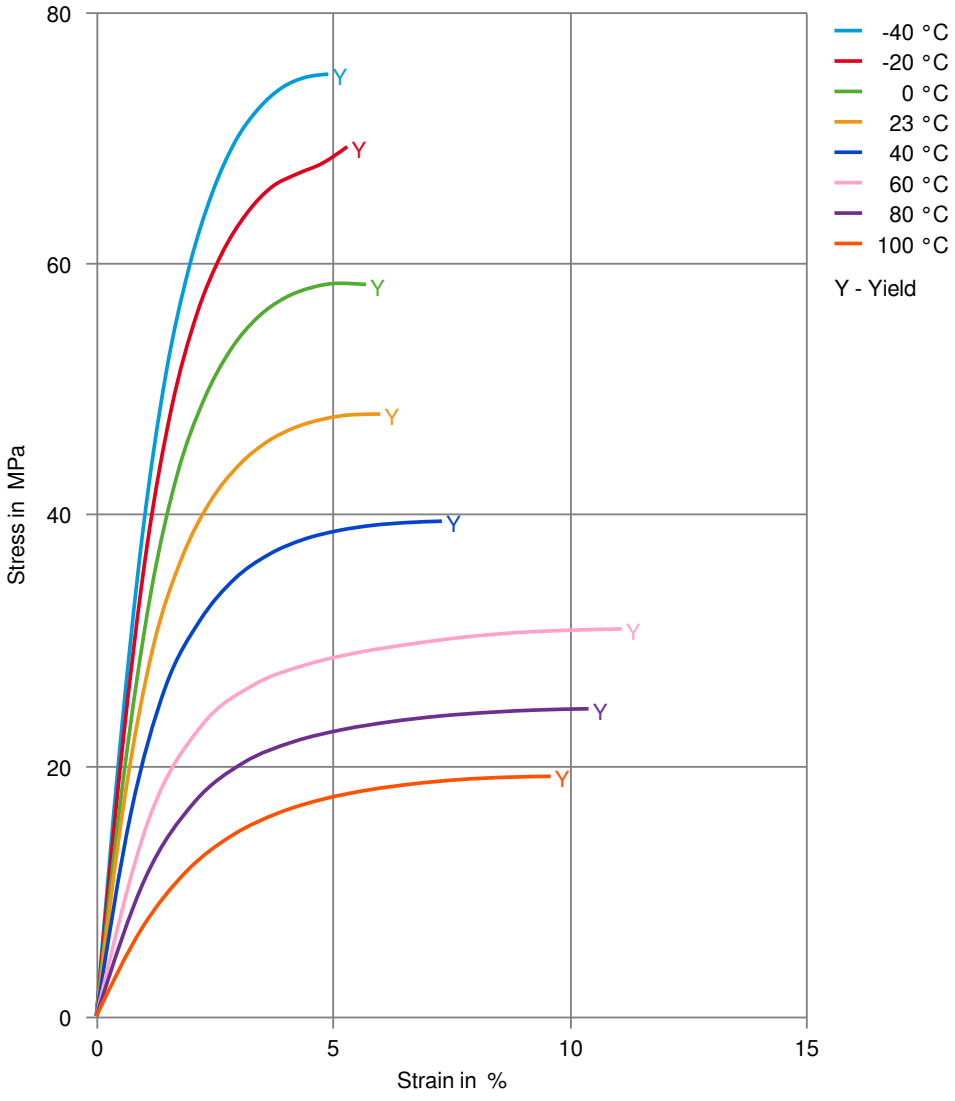
Stress-strain



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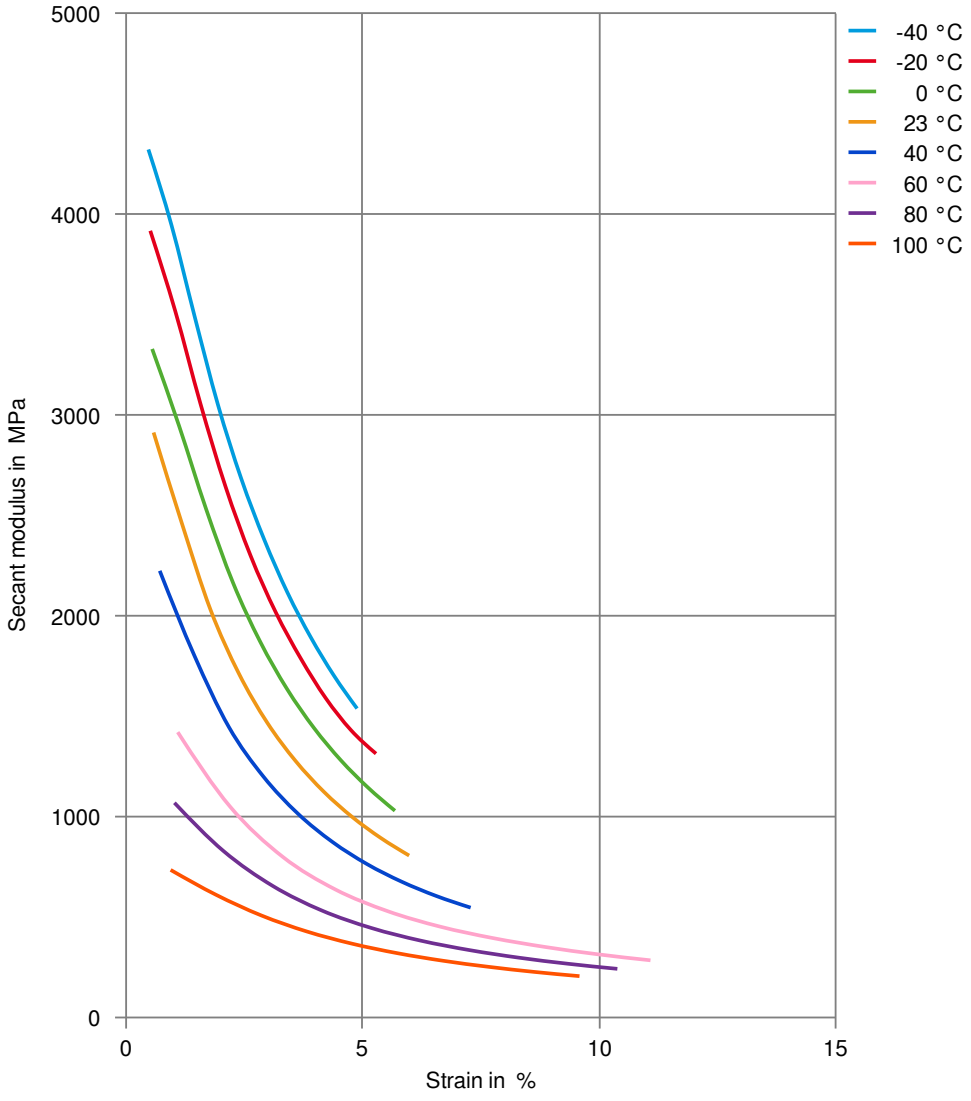
Secant modulus-strain



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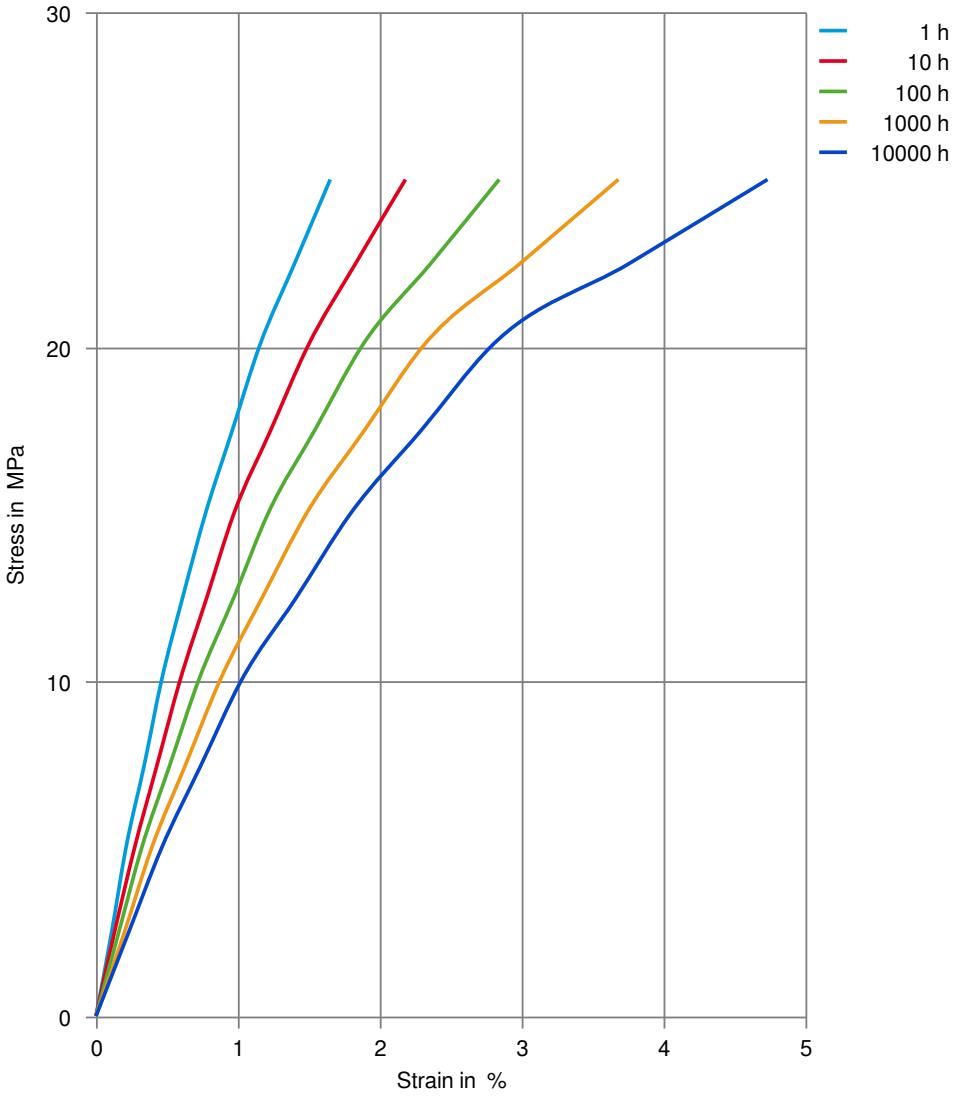
Stress-strain (isochronous) 23 °C



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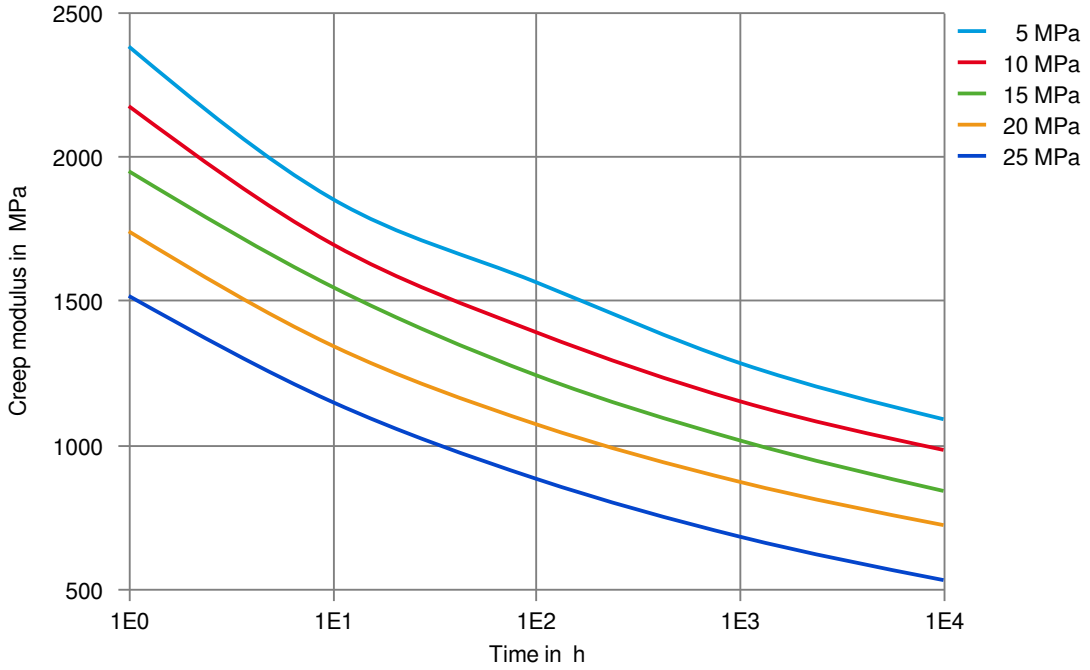
Creep modulus-time 23 °C



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